Supplier Information Company name* Contact Name	IPC ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
Company name* Company unique ID	752-21.1											als and Mf	g Informat	ion	
Semilar Semi	upplier Informa	ation						·							
Title - Contact Name Product Envistewards Uthorized Representative* Title - Representative Title - Compliance NA Product Envis Compliance NA Product Envis Compliance NA Product Envis Compliance NA Product Envis Compliance NA Nanufacturing Site Weight* UOM Unit Title - Representative Nanufacturing Proccess Information Nanufacturing Site Nanufacturi	Company name* Company unique ID					Unique ID Authority					Response Date*				
Product-Env-Stewards Product Enviro Compliance Product-Env-Stewards Prod	nsemi											2025-06-07			
Title - Representative* Product-Env-Stewards Product Enviro Compliance NA Product-Env-Stewards Requester Item Number Mfr Item Number Mfr Item Number Bffective Date Version Manufacturing Site Weight* UOM Unit Township Each Manufacturing Process Information Terminal Plating / Grid Array Material Terminal Base Alloy Matter Tin (Sn) - annealed CU Alloy Township Comments Evel 1 - maximum time at peak temperature during soldering is 10-30 seconds	Contact Name		·	Title - Contact			I	Phone - Contact*				Email - Contact*			
Product-Env-Stewards Product Enviro Compliance NA Product-Env-Stewards@onsemi.com Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM Unit To Compliance NA UNIT To Compliance NA UOM Unit To Compliance NA	Product-Env-Stewar	eds		Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com			
Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM Unit To Description of the Number of Reflow Cycles and Descr	Authorized Representative* Title - Ro				le - Representative			Phone - Representative*			Email - Representative*				
BAV70DXV6T1G SS SOT563 SWITCH DIODE 2025-06-07 CN1 2.72 mg Each	Product-Env-Stewards Produc				roduct Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
Manufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds Somments Evel 1 - maximum time at peak temperature during soldering is 10-30 seconds	Requester	Item Number	Mfr Item Number		Mfr Item Name			Effective Date	Version	N	Manufacturing Site		Veight*	UOM	Unit Type
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or more information regarding material composition please refer to page 3															

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimuly and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct tion member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of						
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.06	mg	Supplier	Silicon (Si)	7440-21-3		0.06	mg
Lead Frame	1.18	mg	Supplier	Silver (Ag)	7440-22-4		0.21	mg
			В	Nickel (Ni)	7440-02-0		0.3646	mg
			Supplier	Iron (Fe)	7439-89-6		0.5039	mg
			Supplier	Copper (Cu)	7440-50-8		0.1015	mg
Mold Compound-Black	1.4	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.14	mg
			Supplier	Carbon Black (C)	1333-86-4		0.007	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.203	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		0.91	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.14	mg
Plating	0.06	mg	Supplier	Tin (Sn)	7440-31-5		0.06	mg
Wire Bond - Cu	0.02	mg	Supplier	Copper (Cu)	7440-50-8		0.02	mg